

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:		DIVISIONAL PATENT APPLICATION		
Inventors:	Wei Pan, David R. Evans and Sheng Teng Hsu) January 21, 2004		
Serial No.:	Unknown) Attorney Docket No. O SLA0861 (SLA0603D)		
Filed:	Herewith	, , , , , , , , , , , , , , , , , , ,		
Title:	INTEGRATED CIRCUIT STRUCTURE WITH COPPER INTERCONNECT) Parent Application: 700 100 100 100 100 100 100 100 100 100		
Assignee:	Sharp Laboratories of America, Inc.) Examiner: Thao P. Le) Anticipated Classification:) Class: 257) Subclass: 565)		

CERTIFICATE OF MAILING BY "EXPRESS MAIL" UNDER 37 C.F.R. 1.10

"Express Mail" mailing label number ER501212827US Date of Mailing: <u>January 21, 2004</u>

I hereby certify that this correspondence is being deposited With the United States Postal Service, utilizing the "Express Mail" Post Office to Addressee" service addressed to Mail Stop PATENT APPLICATION, Hon. Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, and mailed on the above Date of Mailing with the above "Express Mail" mailing label number.

Victoria Woods

Signature Date: January 21, 2004

DIVISIONAL APPLICATION UNDER 37 C.F.R. §1.53(b)

Mail Stop PATENT APPLICATION Hon. Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450 Sir:

The undersigned, attorney-of-record in parent application Serial No. 10/140,460, filed May, 2002, entitled "Ultra Thin Tungsten Metal Films Used as Adhesion Promoter Between Barrier Metals and Copper," hereby requests the filing of a Divisional Application under the provisions of 37 C.F.R. §1.53(b).

<u>Identification of the Parent of the Present Divisional Application:</u>

Serial No.:

10/140,460

Filed:

May 6, 2002

Title:

Ultra Thin Tungsten Metal Films Used as Adhesion

Promoter Between Barrier Metals and Copper

Inventors:

Wei Pan, David R. Evans, and Sheng Teng Hsu

Status:

Pending

Copy of Present Divisional Application:

Enclosed is a copy of the present divisional application which incorporates the following changes from the as-filed specification and drawings in parent application Serial No. 10/140,460: The titled has been changed, an introductory cross-reference section has been added on page 1, and formal drawings have replaced the as-filed informal drawings. The present divisional application includes the following papers:

X	No. of Pages in Specification	: 12	No. of Claims:	
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X No. of Sheets of Drawings: 2 Formal: X or Informal: ...

X Copy of the Declaration (signed by all inventors) in parent application Serial No. 10/140,460.

X Copy of the Power of Attorney in parent application Serial No. 10/140,460.

Parent application Serial No. 10/140,460, filed May 6, 2002, entitled "Ultra Thin Tungsten Metal Films Used as Adhesion Promoter Between Barrier Metals and Copper," is hereby incorporated herein by reference.

Delete the Following Inventor(s) for This Application: None

Amendments:

X Please amend the enclosed specification as follows:

Cancel claims 1-18.

Filing Fee

The Divisional Patent Application filing fee is calculated after cancellation of claims 1-18, as shown below:

	No. Filed	No.		Rate Small Entity/ Other Than	
		Extra		Small Entity	·
Basic				\$385.00	
Fee				\$770.00	\$ 770.00
Total				\$ 9.00	
Claims 3	(<u>20)</u>	= 0	X	\$18.00 =	\$ 00.00
Independent			-	\$43.00	,
Claims 1	<u>(3)</u>	= 0	X	\$86.00 =	\$ 00.00
First Presentation of				\$145.00	
Multiple Depend	lent Claim(s)	0		\$290.00 =	\$ 00.00
	Total PA	TENT APPLIC	CATIC	N FILING FEE	\$ 770.00

The total fee associated with this communication is as follows:

Patent application filing fee \$ 770.00 ======

TOTAL FEE DUE: \$ 770.00

Method of Payment of Fees

- __ A check in the amount of the TOTAL FEE DUE is enclosed.
- Please charge Deposit Account No. 19-1457 in the amount of \$ 770.00.
 A duplicate copy of this authorization is enclosed.
- X The Commissioner is hereby authorized to charge underpayment of any fees associated with this communication, or credit any overpayment, to Deposit Account No. 19-1457. A duplicate copy of this authorization is enclosed.

Customer Number

The Customer Number of the undersigned attorney is:

27518

Correspondence Address

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Respectfully submitted,

David C. Ripma Reg. No. 27,672

Data.

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